

- ✓ Board size max. 510 x 510 mm
- ✓ Electro dynamic solder pump
- ✓ Live image camera
- ✓ Automatic solder feeding
- ✓ Offline programming



# Selective Soldering System

## 640.20



SYSTEC ENTWICKLUNG & FERTIGUNG

# Technical description

■ In modern electronic manufacturing the number of PCBs with assembled SMDs on both sides is growing more and more. If there are also TH components to be soldered this is only possible with high effort when using a normal wave soldering systems.

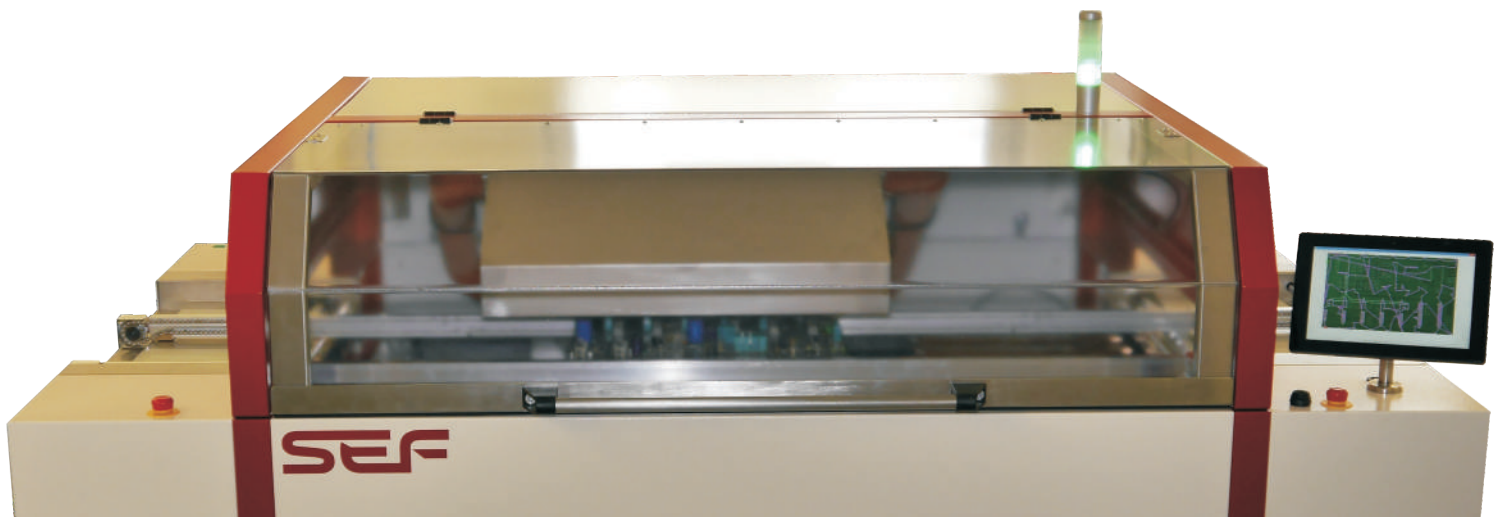
The 640.20 is a full-automatic selective soldering system for small and middle sized production lots. The system is operated with the help of a 7" tablet computer. The programming of the solder joints can be easily done by scanning the PCB and marking the required solder joints.

The maximum PCB size is 510 mm x 510 mm. The feeding of the PCBs takes place via a pin chain conveyor. Thereby the **640.20** can be used in batch mode (PCB feeding and discharge from the same side) or in inline mode (PCB is passing through the system). A SMEMA interface is available for the communication with upstream or downstream devices.

A drop-jet dosing valve ensures the flux fill-up with high positioning accuracy. A light barrier is monitoring the presence of the flux stream. Afterwards the flux will be activated with the help of a preheating module with quartz glass IR heaters.

The soldering is provided by a low-maintenance electromagnetic pump and wettable solder nozzles under the supply of nitrogen. The soldering nozzles are available with different diameters. The movable solder pot has a controlled volume of 10 kg. If necessary more solder will be fed automatically.

The soldering can be watched with the help of a camera and a monitor. A lamp pole shows the status of the machine.



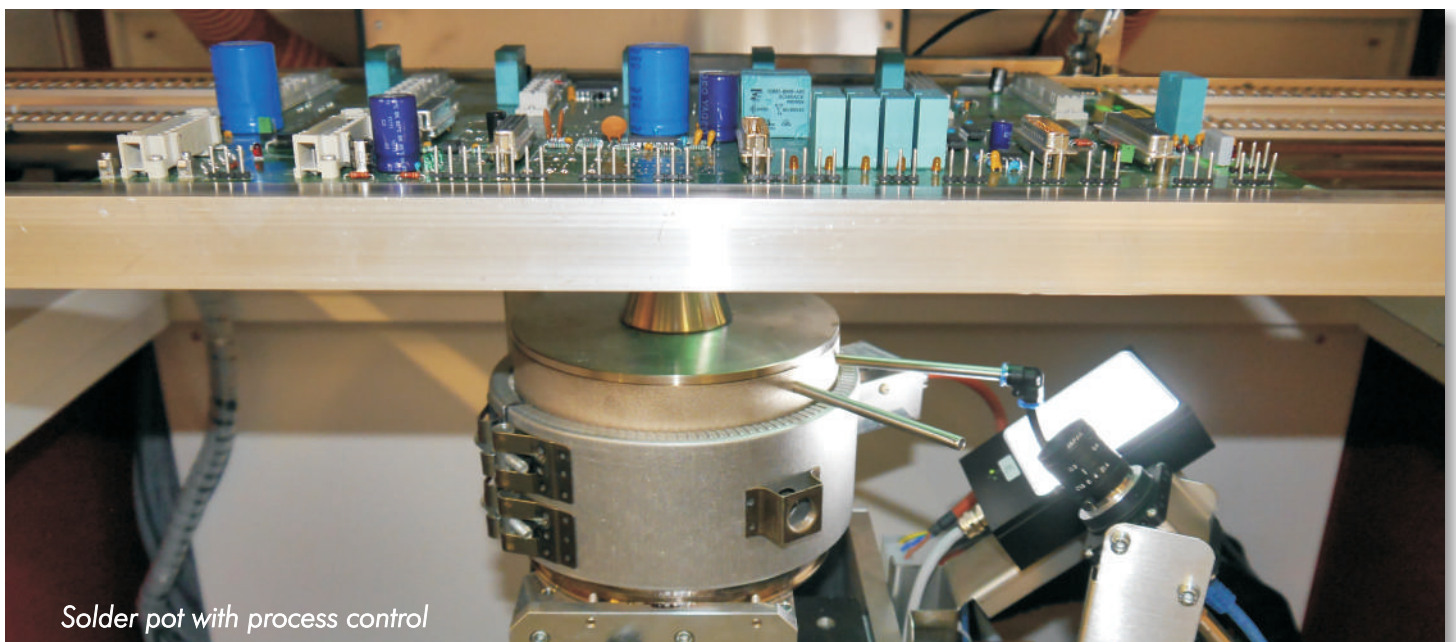
## Technical data 640.20

Length	2000 mm
Width	1250 mm
Height incl. light pole	1450 mm
Max. board size	510 mm x 510 mm
Volume solder pot	10 kg
Heating power solder pot	2,5 kW
Max. movement speed solder pot	2,5 m/min
Volume flux reservoir	1,5 l
Heating power preheating	4,8 kW
Connections	1 6A CEECON compressed air: 5 bar nitrogen: 5 bar
Interfaces	Network - WLAN - SITEMA - USB



## All inclusive:

- ✓ Electro dynamic solder pump without moving parts
- ✓ Height measurement of the solder wave
- ✓ Offline programming
- ✓ Electrical working width adjustment
- ✓ Automatic solder feeding
- ✓ Camera



Solder pot with process control



## *Ready for Industry 4.0*

- ✓ Automatical monitoring of:
  - ✓ all drives
  - ✓ all heating elements
  - ✓ solder volume
  - ✓ flux volume
- ✓ Status message via LAN and WLAN
- ✓ Remote control via Smartphone or Tablet
- ✓ USB connection

SEF Systec GmbH  
Kringelsburg 2a  
21379 Scharnebeck  
GERMANY

T. +82 (0)2 3141 0889  
F. +82 (0)2 3141 8890  
E. [info@namaSMT.com](mailto:info@namaSMT.com)  
W. [www.namaSMT.com](http://www.namaSMT.com)



**SYSTEC ENTWICKLUNG & FERTIGUNG**